

September 2008

FGH20N60UFD 600V, 20A Field Stop IGBT

Features

- · High current capability
- Low saturation voltage: V_{CE(sat)} =1.8V @ I_C = 20A
- High input impedance
- · Fast switching
- RoHS compliant

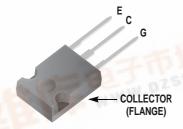
Applications

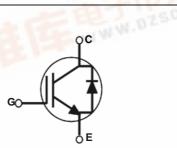
Induction Heating, UPS, SMPS, PFC



General Description

Using Novel Field Stop IGBT Technology, Fairchild's new series of Field Stop IGBTs offer the optimum performance for Induction Heating, UPS, SMPS and PFC applications where low conduction and switching losses are essential.





Absolute Maximum Ratings

Symbol	Description		Ratings	Units
V _{CES}	Collector to Emitter Voltage		600	V
V _{GES}	Gate to Emitter Voltage		± 20	V
I _C	Collector Current	$@ T_C = 25^{\circ}C$	40	А
10	Collector Current	$@ T_C = 100^{\circ}C$	20	Α
I _{CM (1)}	Pulsed Collector Current	$@ T_C = 25^{\circ}C$	60	А
P _D	Maximum Power Dissipation	@ $T_C = 25^{\circ}C$	165	W
. В	Maximum Power Dissipation	$@ T_C = 100^{\circ}C$	66	W
TJ	Operating Junction Temperature		-55 to +150	°C
T _{stg}	Storage Temperature Range		-55 to +150	°C
TL	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300 41 41	°C

Notes:

1: Repetitive rating: Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter Parameter	Тур.	Max.	Units
R _{θJC} (IGBT)	Thermal Resistance, Junction to Case	-	0.76	°C/W
R _{θJC} (Diode)	Thermal Resistance, Junction to Case	-	2.51	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	-	40	°C/W

Package Marking and Ordering Information

D	evice Marking	Device	Package	Packaging Type	Qty per Tube	Max Qty per Box
	FGH20N60UFD	FGH20N60UFDTU	TO-247	Tube	30ea	=

Electrical Characteristics of the IGBT $T_C = 25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Charac	teristics					
BV _{CES}	Collector to Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250\mu A$	600	-	-	V
$\frac{\Delta BV_{CES}}{\Delta T_{J}}$	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250\mu A$	-	0.6	-	V/°C
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$	-	-	250	μА
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$	-	-	±400	nA
On Charac	teristics					
V _{GE(th)}	G-E Threshold Voltage	$I_{C} = 250 \mu A, V_{CE} = V_{GE}$	4.0	5.0	6.5	V
*GE(th)	C 2 Thiodhold Vollage	$I_C = 20A, V_{GE} = 15V$	-	1.8	2.4	V
V _{CE(sat)}	Collector to Emitter Saturation Voltage	I _C = 20A, V _{GE} = 15V, T _C = 125°C	-	2.0	-	V
Dynamic C	haracteristics					
C _{ies}	Input Capacitance		-	940	-	pF
C _{oes}	Output Capacitance	$V_{CE} = 30V_{,} V_{GE} = 0V_{,}$ f = 1MHz	-	110	-	pF
C _{res}	Reverse Transfer Capacitance	1 = 11/11/12	-	40	-	pF
	Characteristics	T		1	T	I
t _{d(on)}	Turn-On Delay Time		-	13	-	ns
t _r	Rise Time		-	17	-	ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 400V, I_C = 20A,$	-	87	-	ns
t _f	Fall Time	$R_G = 10\Omega$, $V_{GE} = 15V$, Inductive Load, $T_C = 25^{\circ}C$	-	32	64	ns
E _{on}	Turn-On Switching Loss		-	0.38	-	mJ
E _{off}	Turn-Off Switching Loss		-	0.26	-	mJ
E _{ts}	Total Switching Loss		-	0.64	-	mJ
t _{d(on)}	Turn-On Delay Time		-	13	-	ns
t _r	Rise Time		-	16	-	ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 400V, I_{C} = 20A,$	-	92	-	ns
t _f	Fall Time	$R_G = 10\Omega$, $V_{GE} = 15V$, Inductive Load, $T_C = 125^{\circ}C$	-	63	-	ns
E _{on}	Turn-On Switching Loss		-	0.41	-	mJ
E _{off}	Turn-Off Switching Loss		-	0.36	-	mJ
E _{ts}	Total Switching Loss		-	0.77	-	mJ
Q_g	Total Gate Charge	V 400V I 00A	-	63	-	nC
Q _{ge}	Gate to Emitter Charge	$V_{CE} = 400V, I_{C} = 20A,$ $V_{GE} = 15V$	-	7	-	nC
Q_{gc}	Gate to Collector Charge	-GE	-	32	-	nC

Electrical Characteristics of the Diode $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max	Units
V _{FM} Diode Forward Voltage	Diode Forward Voltage	I _E = 10A	$T_C = 25^{\circ}C$	-	1.9	2.5	V
		$T_{\rm C} = 125^{\rm o}{\rm C}$	-	1.7	-		
t	Diode Reverse Recovery Time		$T_C = 25^{\circ}C$	-	34	-	ns
111		l _{ES} =10A, dl _{ES} /dt = 200A/μs	$T_{\rm C} = 125^{\rm o}{\rm C}$	-	57	-	
Q _{rr}	Diode Reverse Recovery Charge	1Ες - 10Α, αιξς/αι - 200Α/μ3	$T_C = 25^{\circ}C$	-	41	1	nC
~II			$T_{\rm C} = 125^{\rm o}{\rm C}$	-	96	-]

Figure 1. Typical Output Characteristics

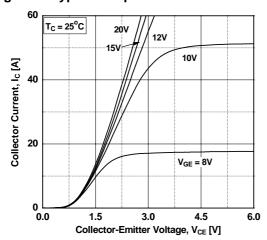


Figure 3. Typical Saturation Voltage Characteristics

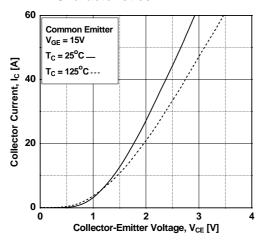


Figure 5. Saturation Voltage vs. Case
Temperature at Variant Current Level

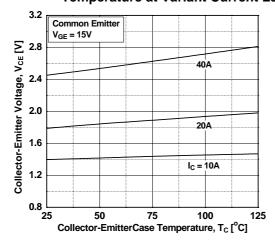


Figure 2. Typical Output Characteristics

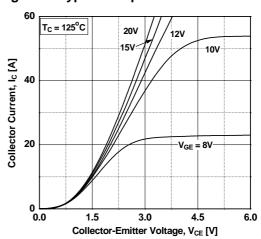


Figure 4. Transfer Characteristics

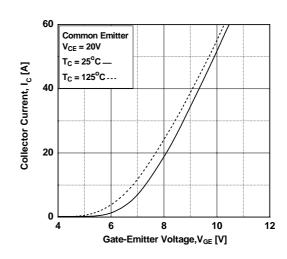


Figure 6. Saturation Voltage vs. V_{GE}

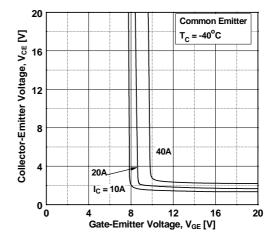


Figure 7. Saturation Voltage vs. V_{GE}

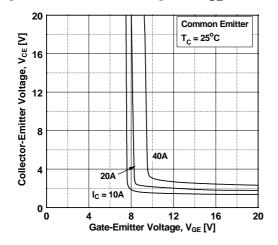


Figure 9. Capacitance Characteristics

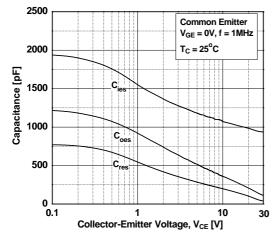


Figure 11. SOA Characteristics

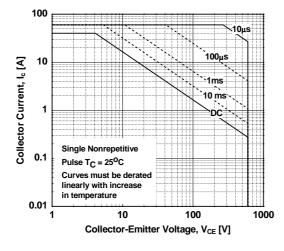


Figure 8. Saturation Voltage vs. V_{GE}

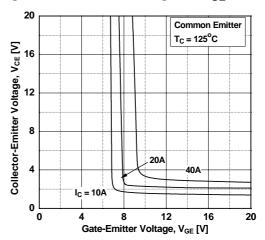


Figure 10. Gate charge Characteristics

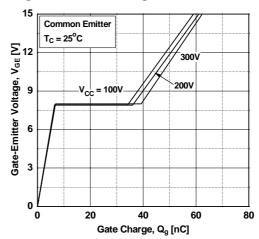


Figure 12. Turn-on Characteristics vs.

Gate Resistance

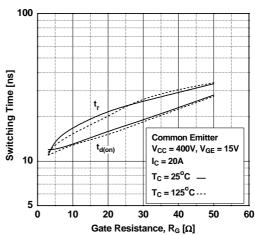


Figure 13. Turn-off Characteristics vs.
Gate Resistance

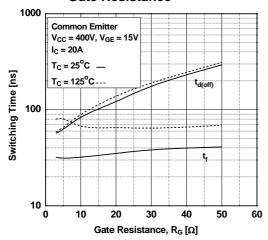


Figure 15. Turn-off Characteristics vs. Collector Current

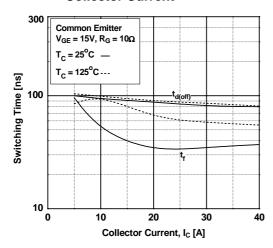


Figure 17. Switching Loss vs. Collector Current

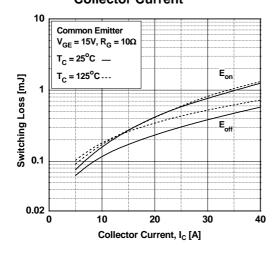


Figure 14. Turn-on Characteristics vs. Collector Current

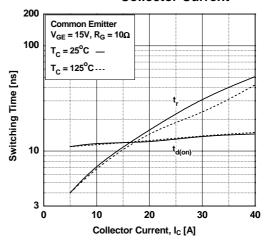


Figure 16. Switching Loss vs.
Gate Resistance

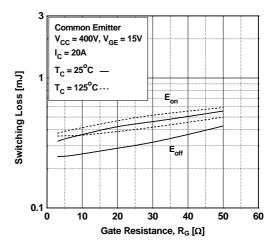


Figure 18. Turn off Switching SOA Characteristics

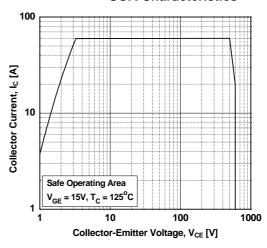


Figure 19. Forward Characteristics

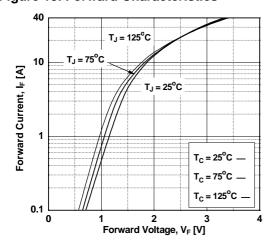


Figure 20. Reverse Current

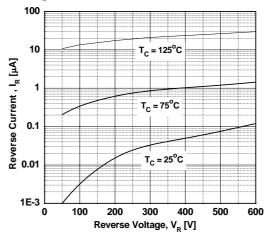


Figure 21. Stored Charge

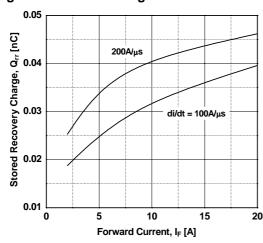


Figure 22. Reverse Recovery Time

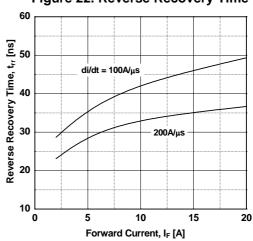
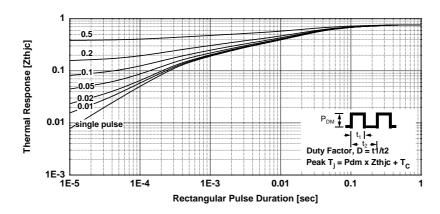


Figure 23. Transient Thermal Impedance of IGBT



Mechanical Dimensions TO247AB (FKS PKG CODE 001) A +/-0.07 MATTED AREA 4.700 **₡**1,500X0,15DP. (3X) POLISH AREA 5.50 Ø 3.580±0.05 Ø 5.000 MARKING-POLISH AREA MATTED AREA R0.500 (4x) POLISH AREA 1.65±0.12 1.64 2.54±0.12 -1.26±0.09 0.600±0.09 5.560 (TYP) - 5.560 (TYP) OLISH AREA APPLY TO ALL CORNER RADIUS OLISH AREA





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